



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2024-04-01
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32C011F4U3TR	P5E4*443XXXZ	A	9996	2024-04-01
	Amount	UoM	Unit type	ST ECOPACK Grade
	14.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3x3x0.6	20	flat	
Comment	Package : AOAS UFQFPN 3X3X0.6 20L 0.5 MM PITCH 8177031			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	PSE4*443XXZ				6999899.0	100000.2
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.871	mg	#N/A	die	Silicon (Si)	7440-21-3		0.787	mg	903559	56210
				#N/A	metallization	Aluminium (Al)	7429-90-5		0.004	mg	4592	286
				#N/A	metallization	Copper (Cu)	7440-50-8		0.036	mg	41332	2571
				#N/A	metallization	Tantalum (Ta)	7440-25-7		0.012	mg	13777	857
				supplier	Passivation	Silicon Nitride	12033-89-5		0.009	mg	10333	643
Leadframe (C7025)	Copper and its alloy	4.594	mg	#N/A	Passivation	Silicon Oxide	7631-86-9		0.023	mg	26406	1643
				supplier	alloy	Copper (Cu)	7440-50-8		4.419	mg	962000	315620
				supplier	alloy	Nickel (Ni)	7440-02-0		0.138	mg	30000	9856
				supplier	alloy	Silicon (Si)	7440-21-3		0.030	mg	6500	2143
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.007	mg	1500	500
Leadframe Plating (PPF)	M-011 Other inorganic materials	0.216	mg	supplier	coating	Nickel	7440-02-0		0.201	mg	928857	14356
				supplier	coating	Palladium	7440-05-3		0.008	mg	35572	571
				supplier	coating	Gold	7440-57-5		0.004	mg	19964	286
				supplier	coating	Silver	7440-22-4		0.003	mg	15608	214
				supplier	glue	Silicon dioxide	7631-86-9		0.021	mg	600000	1500
Glue epoxy (ATB-F125)	M-011 Other inorganic materials	0.035	mg	supplier	glue	Modified Epoxy Resin	Proprietary		0.003	mg	100000	214
				supplier	glue	Poly[oxy[[2-oxirany]-1,2-cyclohexanediy]], n-H	244772-00-7		0.003	mg	100000	214
				supplier	glue	Phenol-formaldehyde polymer	9003-35-4		0.003	mg	100000	214
				supplier	glue	Epoxy resin	25068-38-6		0.003	mg	100000	214
				supplier	bonding wire	Gold (Au)	7440-57-5		0.009	mg	999900	643
Bonding Wire (Au)	M-011 Other inorganic materials	0.009	mg	supplier	molding compound	Epoxy Resin	Proprietary		0.540	mg	70000	38569
				supplier	molding compound	Phenol Resin	Proprietary		0.193	mg	25000	13785
				supplier	molding compound	Silica(Amorphous) A	60676-86-0		5.557	mg	720000	396900
				supplier	molding compound	Silica(Amorphous) B	7631-86-9		1.389	mg	180000	99207
				supplier	molding compound	Carbon Black	1333-86-4		0.039	mg	5000	2786
Encapsulation (G700v)	M-011 Other inorganic materials	7.719	mg	supplier	external plating	Nickel	7440-02-0		0.520	mg	928857	37140
				supplier	external plating	Palladium	7440-05-3		0.020	mg	35572	1428
				supplier	external plating	Gold	7440-57-5		0.011	mg	19964	786
				supplier	external plating	Silver	7440-22-4		0.009	mg	15608	643
				supplier	external plating	Silver	7440-22-4		0.009	mg	15608	643